

High-performance polishing materials for glass

MIREK™

Application

- Polishing materials for liquid crystal glass, hard disk, photomask, etc

Summary

- CeO₂ abrasive enable high-rate, low-damage processing.
- Multiple product lines suitable for wide application from primary to final polishing.



Powder



Slurry

Product name	Properties	Average particle size (μm)	Main applications
		Laser diffraction	
HL05	Powder	0.5~0.9	For final polishing
HL10		0.8~1.3	For final polishing
HL21		1.0~1.4	For final polishing
HL30		1.2~1.7	For primary polishing
HL40		1.7~2.5	For primary polishing
HL030CS	Slurry	0.2~0.3	For final polishing
HL020CS		0.1~0.2	For final polishing
K020C		0.08~0.15	For final polishing /Alternatives to colloidal silica /Developed products



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